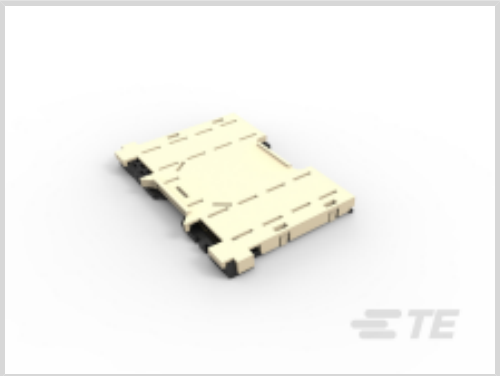




Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 Sockets



IC Socket Type: **LGA 3647**

Number of Positions: **1824**

Contact Mating Area Plating Material Thickness: **[30 µin]**

Centerline (Pitch): **.86 mm, .99 mm [.034 in, .039 in]**

Termination Method to Printed Circuit Board: **Surface Mount - Solder Ball**

[All LGA 3647 Sockets \(0\)](#)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	1824
Grid Spacing	.9906 x .8585 mm[.039 x .0338 in]

Body Features

Frame Style	C Shape
-------------	---------

Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 µin
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
---	-----------------------------

Mechanical Attachment



Connector Mounting Type	Board Mount
-------------------------	-------------

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.86 mm, .99 mm[.034 in][.039 in]

Usage Conditions

Operating Temperature Range	-25 - 100 °C[-13 - 212 °F]
-----------------------------	----------------------------

Operation/Application

Circuit Application	Signal
---------------------	--------

Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

Packaging Features

Tray Color	Black
Packaging Method	Tray

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C







Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits






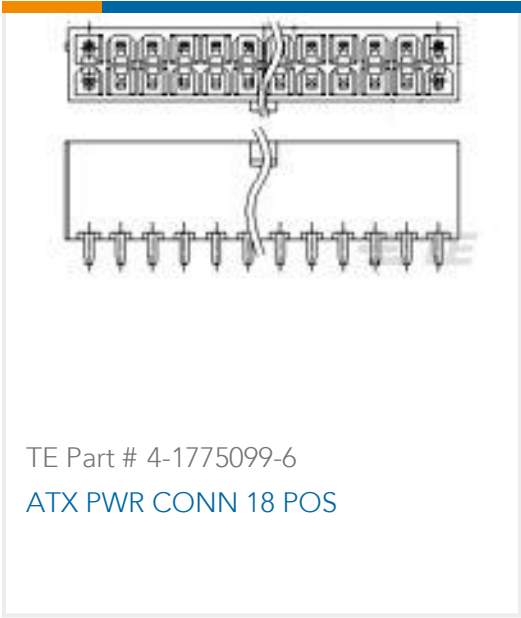




as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

 <p>TE Part # 2821719-1 IFP/LEC CBL ASSY 2 PORT TYPE A STR</p>	 <p>TE Part # 2821719-2 IFP/LEC CBL ASSY 2 PORT TYPE A STR</p>	 <p>TE Part # 2821719-3 IFP/LEC CBL ASSY 2 PORT TYPE A STR</p>	 <p>TE Part # 2821719-4 IFP/LEC CBL ASSY 2 PORT TYPE A STR</p>
 <p>TE Part # 2821720-1 IFP/LEC CBL ASSY 2 PORT TYPE A STR INV</p>	 <p>TE Part # 2821720-2 IFP/LEC CBL ASSY 2 PORT TYPE A STR INV</p>		

Customers Also Bought

 <p>TE Part # 9-2199155-4 DDR4 DIMM 288 PIN SMT TYPE</p>	 <p>TE Part # 2-2129710-8 RIGHT SIDE LGA3647-1 SOCKET-P1 FOR ODM</p>	 <p>TE Part # 6-1734598-1 1.25 WTB HDR DIP, L=2.3, 8 POS</p>	 <p>TE Part # 6450824-9 MBXL VERT HDR STR 7ACP</p>
 <p>TE Part # 1-2041554-2 PCI-E, DIP, 98POS, T&R PACKAGE</p>	 <p>TE Part # 4-1775099-6 ATX PWR CONN 18 POS</p>	 <p>TE Part # 2-2041242-1 30PCI-E CARD EDGE, 98 POS, 30U",</p>	 <p>TE Part # 2322144-2 MBXL R/A HDR STR 1ACP+8S+1ACP, HF</p>

Documents

Product Drawings
LEFT SIDE LGA3647-1 SOCKET-P1 FOR ODM

English



CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-2129710-7_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-2129710-7_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-2129710-7_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

LGA 3647 Socket Product Flyer

English

Product Specifications

Application Specification

English